JAE Electronics, Inc.
August 3rd, 2026

ENG-E25-036-1 - Distributors

PCN (Process Change Notice)

IL-AG9-2S-S3C1
Additional Production Location &
Replacement Mold Die
(1N,1P,1Q,1R)
To Keep Production Capacity

Part Number	3 Existing Mold Dies with 4 cavities/die	Replacement Mold Die created with 4 cavities	Existing Production Location	Additional Production Location	Completion Mold Die	Proposed PPAP Submission	Start of Mass Production (SOP)
IL-AG9-2S-S3C1	(U,V,W,X), (1E,1F,1G,1H), (1J,1K,1L,1M)	(1N,1P,1Q,1R) to replace (U,V,W,X)	JAE Hirosaki (HAE)	YAMAICHI SEIKO Co., LTD.	February 2025	June 2025 → August 2026	After receiving all approvals

Notes:

- PC = Process Change (Tooling: Transfer, Replacement, Refurbishment, or additional and Parts Produced at Additional Location, etc…)
- PPAP = Production Part Approval Process

1. PC PPAP will only be prepared and provided to customer who already requested and received initial PPAP.
2. If you request PC PPAP documents for this notification, please notify us ASAP.

JAE Connector Div. Proprietary. Copyright @ 2025, Japan Aviation Electronics Industry, Ltd. Confidential